

Canada G2 eUICC SIM

Triple Cut Format



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Triple Cut Format - 2FF, 3FF, 4FF

Product overview

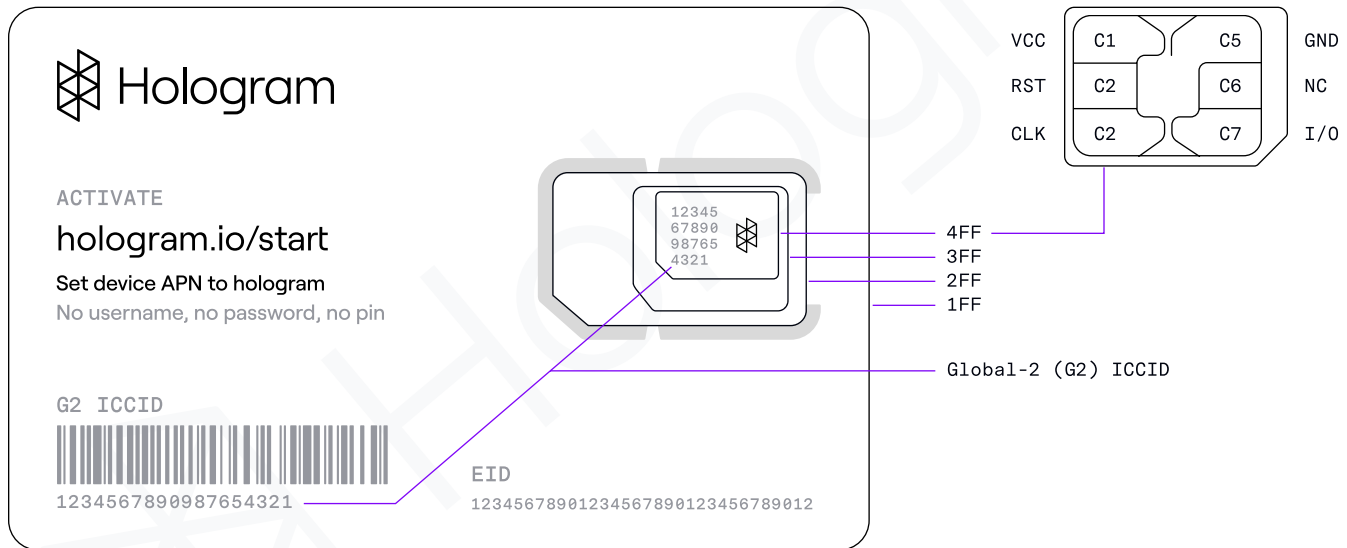
A secure, device-agnostic IoT SIM card for deployments in Canada built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs are eUICC compliant and the Hyper platform remotely updates coverage over-the-air by adding or removing profiles, without requiring you to swap the SIM in your device.

Network availability

Works globally with Hologram's 2G through 4G (LTE) network including LTE-M and NB-IoT where coverage is available. More information:

<https://www.hologram.io/pricing/coverage>

Mechanical specifications



Physical characteristics

Size

Format	Size	Dimensions (mm)
1FF	Full-size	85.6 × 54 × 0.71
2FF	Mini-SIM	25 × 15 × 0.71
3FF	Micro-SIM	15 × 12 × 0.71
4FF	Nano-SIM	12.3 × 8.8 × 0.71

Pin definitions

Pin	Signal	Description
C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

Hardware features

Chip type

Supplier	Samsung
Chip Code	S3FW9FJM

Electrical

Operating Voltage	1.62V to 5.5V
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Hardware characteristics

Grade	Standard
Operational Temperature	-25°C to +85°C
Data Retention	25 years @ 25°C
Write Endurance	500K cycles native, 10M cycles with High Endurance Interface @ 25°C
Memory (NVM)	704 KB
Memory (SRAM)	20 KB

AC electrical parameters standards

ETSI 3GPP TS 102 221 v14.0.0 - UICC-Terminal interface; Physical and logical characteristics
 ISO/IEC 7816, T=0 standard for Cards with contacts – USB electrical interface and operating procedures

Compliance

Chip	 Common Criteria	EAL 4+ CCN-CC-5/2019
OS	 GSMA	Embedded UICC Technical Specification v3.2
	 TRUSTED CONNECTIVITY ALLIANCE	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.3.1
	 GLOBALPLATFORM®	Card Specification Version 2.1.1 Card Specification Version 2.2 Amendments A, B, D & E
Software	 ORACLE® Java Card	Java Card 3 Platform, Classic Edition version 3.0.5
	 3GPP A GLOBAL INITIATIVE	Release 14
Remote SIM provisioning	 GSMA	SGP.01 Embedded SIM Remote Provisioning Architecture v1.1 SGP.02 SGP.16 M2M Compliance Process v1.1
Supplier's Declaration of Conformity		<p>Manufactured according to the following standards:</p> <ul style="list-style-type: none"> • RoHS Directive 2011/65/EU • Reach certification • GSMA SAS-UP • ISO 9001:2015 • ISO 27001 • ISO 14001